

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
RYOJI OKABE	07/17/2015
TOSHIHIKO KARIYA	07/17/2015
NAOKI TODA	07/17/2015
MUNEHIRO NOBUTA	07/17/2015
RECEIVING PARTY DATA	
Name:	MITSUBISHI HEAVY INDUSTRIES PLASTIC TECHNOLOGY CO., LTD.
Street Address:	1, AZA TAKAMICHI, IWATSUKA-CHO, NAKAMURA-KU
City:	NAGOYA-SHI, AICHI
State/Country:	JAPAN
Postal Code:	4530862
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14758518
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SIGNATURE:	/Benjamin J. Hauptman/
DATE SIGNED:	07/30/2015
Total Attachments: 1	
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ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

- 1) Ryoji OKABE
- 2) Toshihiko KARIYA
- 3) Naoki TODA
- 4) Munehiro NOBUTA

who has made a certain new and useful invention, hereby sells, assigns and transfers unto MITSUBISHI HEAVY INDUSTRIES PLASTIC TECHNOLOGY CO., LTD. having a place of business at 1, Aza Takamichi, Iwatsuka-cho, Nakamura-ku, Nagoya-shi, Aichi 4530862 Japan, its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled:

INJECTION MOLDING METHOD AND INJECTION MOLDING DEVICE

- (a) for which an application for United States Letters Patent was filed on June 29, 2015, and identified by United States Patent Application No. 14/758,518; or
- (b) for which an application for United States Letters Patent was executed on

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

1) Ryoji Okabe
 Name: Ryoji OKABE

2015/7/17
 Date

2) Toshihiko Kariya
 Name: Toshihiko KARIYA

2015/7/17
 Date

3) Naoki Toda
 Name: Naoki TODA

2015/7/17
 Date

4) Munehiro Nobuta
 Name: Munehiro NOBUTA

2015/7/17
 Date